
















**Schematic Key for Multilayer and HDI-Technology Build-Ups**

a	b	c	d	e	f	g + h + i
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**06 125 FR4 55 L20.35 P10**

columns and equal kind of positions are separated by "\_". Equal prefixes in one column are reduced to one.

**06\_125\_FR4\_55\_L20.35\_p10**

Layers	in $\mu$	Material	Build-Up	Assembly		
<b>Layer-1</b>	55 $\mu$	Copper		} <b>B</b>		
	100 $\mu$	Prepreg				
	100 $\mu$	Prepreg				
<b>Layer-2</b>	35 $\mu$	Copper				} <b>A1</b>
	200 $\mu$	L-FR4				
<b>Layer-3</b>	35 $\mu$	Copper				} <b>A2</b>
	100 $\mu$	Prepreg				
	100 $\mu$	Prepreg				
<b>Layer-4</b>	35 $\mu$	Copper				
	200 $\mu$	L-FR4				
<b>Layer-5</b>	35 $\mu$	Copper		} <b>B</b>		
	100 $\mu$	Prepreg				
	100 $\mu$	Prepreg				
<b>Layer-99</b>	55 $\mu$	Copper				
					} <b>B</b>	

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